

PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

January 6, 2010

Applicants: Toshihiro TAI et al

Title: PLATED RESIN MOLDED ARTICLES

Serial No.: 10/586 378

Group: 1794

Confirmation No.: 2951

Filed: July 14, 2006

Examiner: Kruer

International Application No.: PCT/JP2005/002827

International Filing Date: February 16, 2005

Atty. Docket No.: 3400.P1434US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

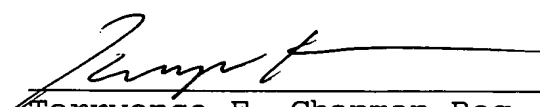
Herewith is an amendment in the above-identified application.

☐ Applicant claims small entity status. See 37 CFR 1.27.☐ The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	( ) SM Entity	Fee
Total Claims	(13 - 20 = 0)		x	\$ 52.00	x	\$ 26.00
Indep. Claims	( 1 - 3 = 0)		x	\$220.00	x	\$110.00
[ ] Multiple Dep. Claim			+	\$390.00	+	\$195.00
* * * TOTAL FILING FEE * * *						\$ 0.00

☐ Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.☐ A Check for \$ is enclosed to cover fees.☒ Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382.

TFC/smd

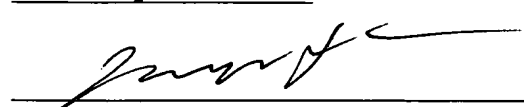
  
Terryence F. Chapman Reg. No. 32 549

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 6, 2010.

130.10/08

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Terryence F. Chapman